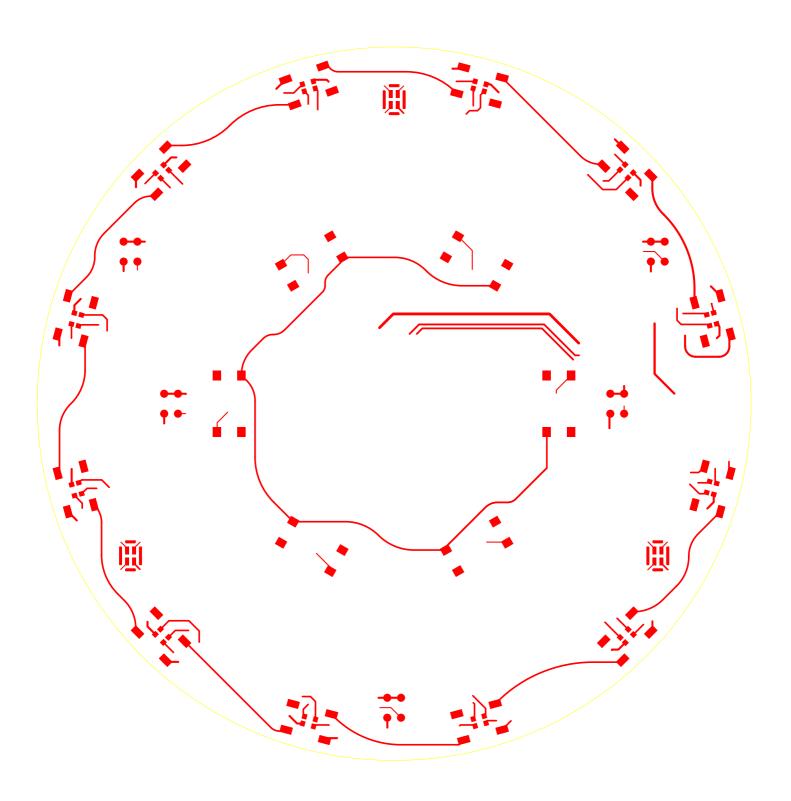


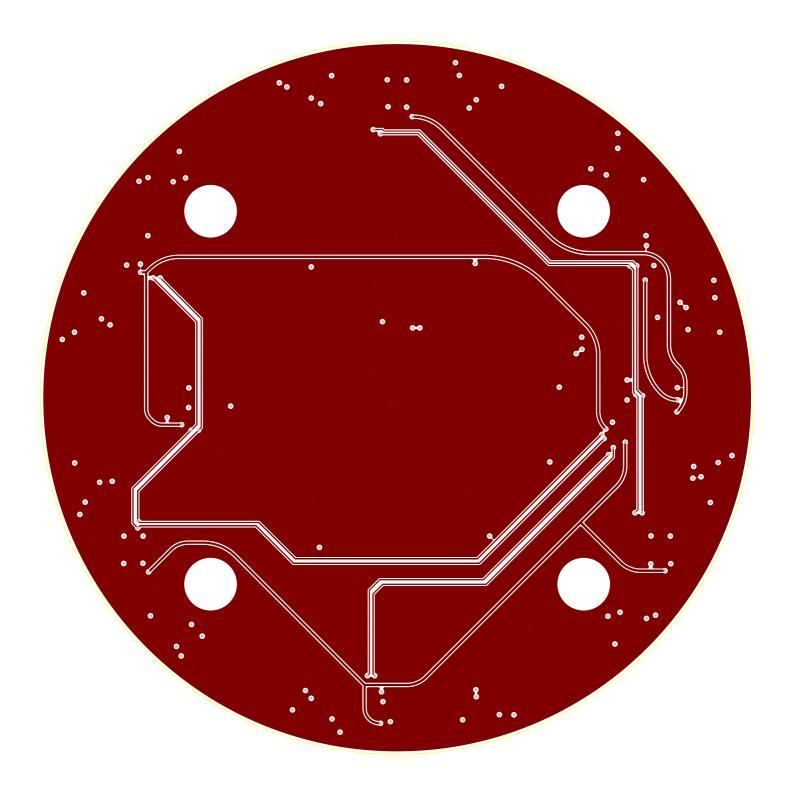
ESPF	ESSIF SYSTEM				
乐鑫信	乐鑫信息科技(上海)股份有限公司				
Title	ESP32-Korvo-Mic	Rev 11			
Task	#31025				
Date	2020.03.16 Mon.				

 1:TOP	展	材料 (FR4)	厚度(
Prepreg	L1_TOP	10Z	1.4
 2:GND		PP(2116*2)	8.6
Core	L2_GND	10Z	1.4
 3:POWER		Core(可谓)	32
Prepreg	L3_POWER	10Z	1.4
 4:Bottom		PP(2116*2)	8.6
	L4_BOTTOM	10Z	1.4



ESPRESSIF SYSTEM					
乐鑫信	乐鑫信息科技(上海)股份有限公司				
Title	ESP32-Koryo-Mic	Rev 1.1			
Task	#31025				
Date	2020.03.16 Non.				

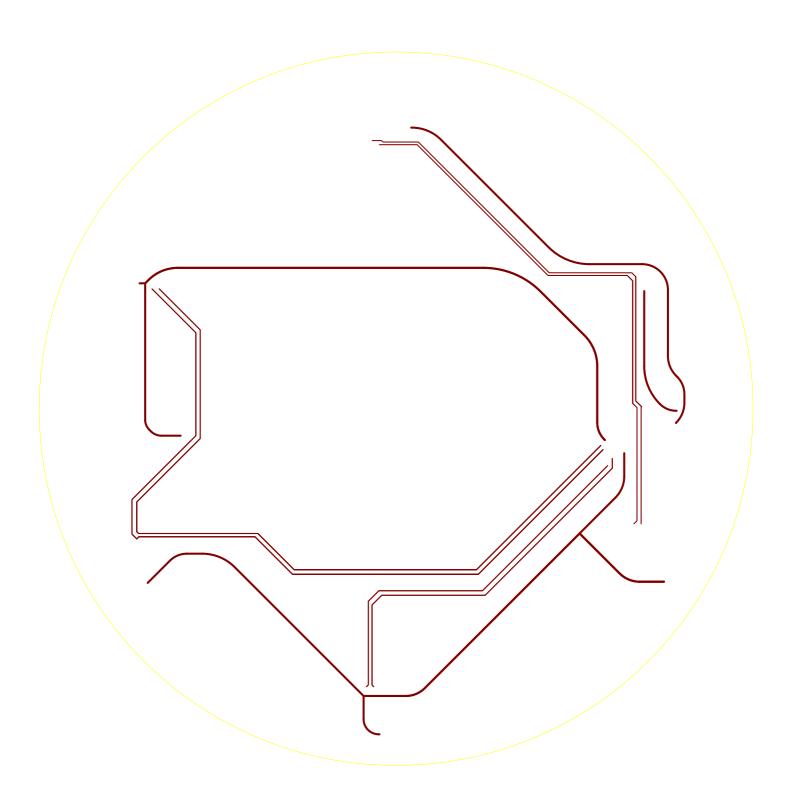
L1:TOP	展	材料 (FR4)	厚度(mil)
Prepreg	L1_TOP	10Z	1.4
L2:GND		PP(2116*2)	8.6
Core	L2_GND	10Z	1.4
L3:POWER		Core(可谓)	32
Prepreg	L3_POWER	10Z	1.4
L4:Bottom		PP(2116*2)	8.6
	L4 BOTTOM	10Z	1.4



ESPRESSIF SYSTEM				
ESFI	ESSIF STOTEM			
乐鑫信息科技(上海)股份有限公司				
Title	ESP32-Korvo-Mic	Rev 11		
Task	#31025			
Date	2020.03.16 Mon.			

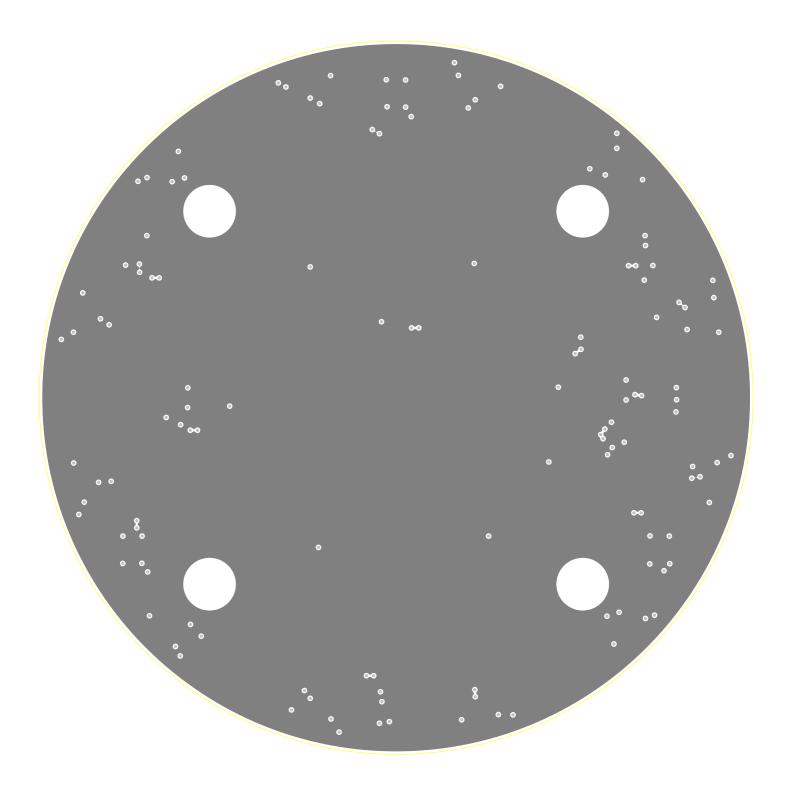
L1:TOP	展
Prepreg	L1_TOP
L2:GND	
Core	L2_GND
L3:POWER	
Prepreg	L3_POWE
L4:Bottom	
	L4_BOTT

层	材料 (FR4)	厚度(mil)
L1_TOP	10Z	1.4
	PP(2116*2)	8.6
L2_GND	10Z	1.4
	Core(=[iii])	32
L3_POWER	10Z	1.4
	PP(2116*2)	8.6
L4_BOTTOM	10Z	1.4
AG DECOMAND		1.61/07



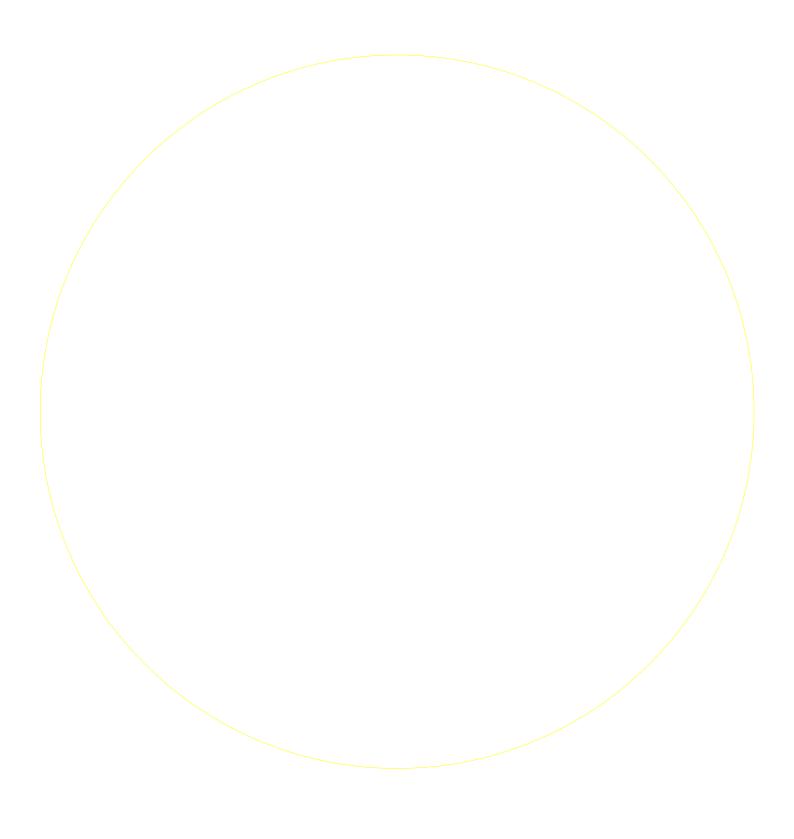
ESPF	RESSIF SYSTEM	
乐森信	(息科技(上海)股份有限公司	
Title	ESP32-Korvo-Mic	Rev L1
Task	#31025	i e
Date	2020.03.16 Mon.	

L1:TOP	展	材料 (FR4)	厚度(mil)
Prepre	L1_TOP	10Z	1.4
L2:GND		PP(2116*2)	8.6
Core	L2_GND	10Z	1.4
L3:POWER		Core(=[iii])	32
Prepre	L3_POWER	10Z	1.4
L4:Bottom		PP(2116*2)	8.6
	L4_BOTTOM	10Z	1.4
	長坪(MM)		1.6MM



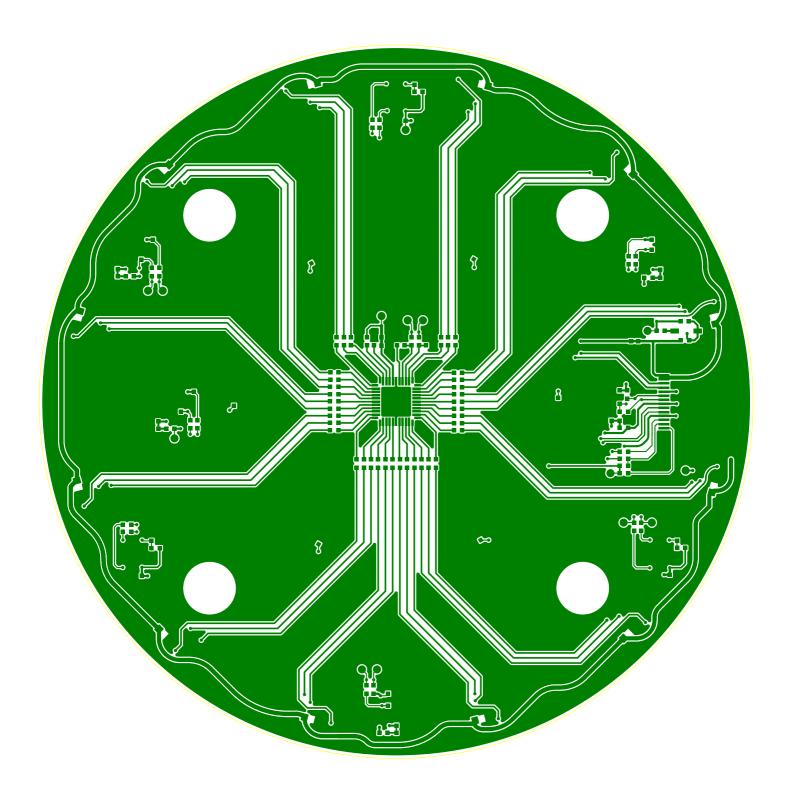
ESPRESSIF SYSTEM				
乐鑫信息科技(上海)股份有限公司				
Title	ESP32-Korvo-Mic	Rev L1		
Task	#31025			
Date	2020.03.16 Non.			

L1:TOP	展	材料 (FR4)	厚度(mil)
Prepri	g L1_TOP	10Z	1.4
L2:GND		PP(2116*2)	8.6
Core	L2_GND	10Z	1.4
L3:POWER	2	Core(=(ii))	32
Prepri	g L3_POWER	10Z	1.4
L4:Bottom		PP(2116*2)	8.6
	L4_BOTTOM	10Z	1.4
	REFF (MM)		1.6MM



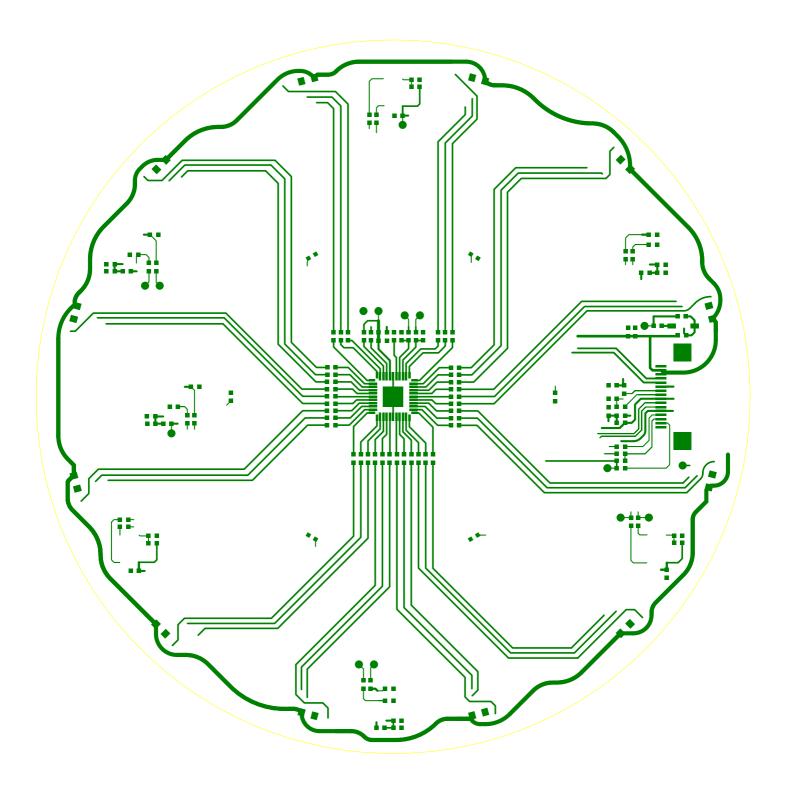
ESPRESSIF SYSTEM				
乐鑫信息科技(上海)股份有限公司				
Title	ESP32-Korvo-Mic	Rev L1		
Task	#31025			
Date	2020 03 16 Mon			

	BETT (MM)		1.6MM
	L4_BOTTOM	10Z	1.4
L4:Bottom		PP(2116*2)	8.6
Prepreg	L3_POWER	10Z	1.4
L3:POWER		Core(可谓)	32
Core	L2_GND	10Z	1.4
L2:GND		PP(2116*2)	8.6
Prepreg	L1_TOP	10Z	1.4
L1:TOP	展	材料 (FR4)	厚度(mil)



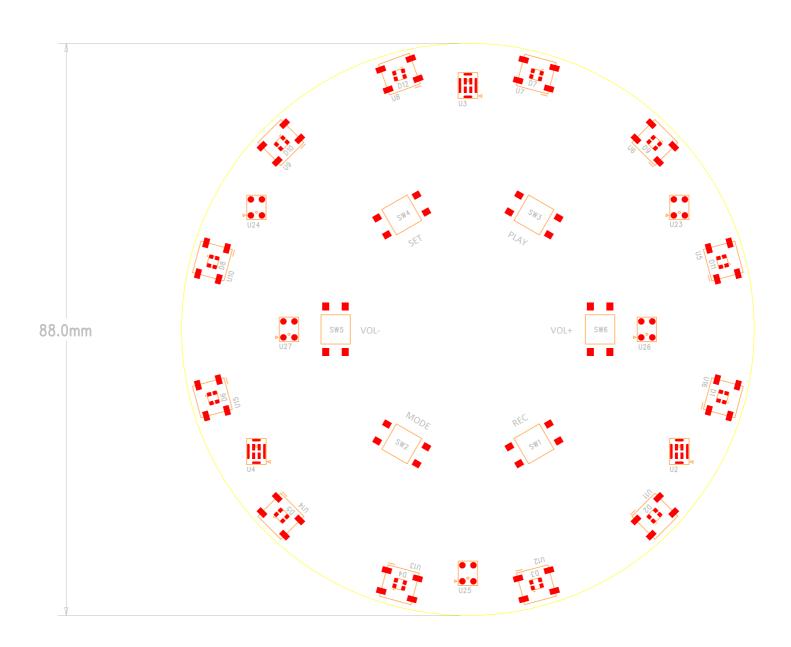
ESPF	RESSIF SYSTEM	
乐鑫信	(息科技(上海)股份有限公司	
Title	ESP32-Koryo-Mic	Rev L1
Task	#31025	·
Date	2020.03.16 Mon.	

L1:TOP	展	材料 (FR4)	厚度(mil)
Prepreg	L1_TOP	10Z	1.4
L2:GND		PP(2116*2)	8.6
Core	L2_GND	10Z	1.4
L3:POWER		Core(=[iii])	32
Prepreg	L3_POWER	10Z	1.4
L4:Bottom		PP(2116*2)	8.6
	L4_BOTTOM	10Z	1.4
	851F(MM)		1.6MM



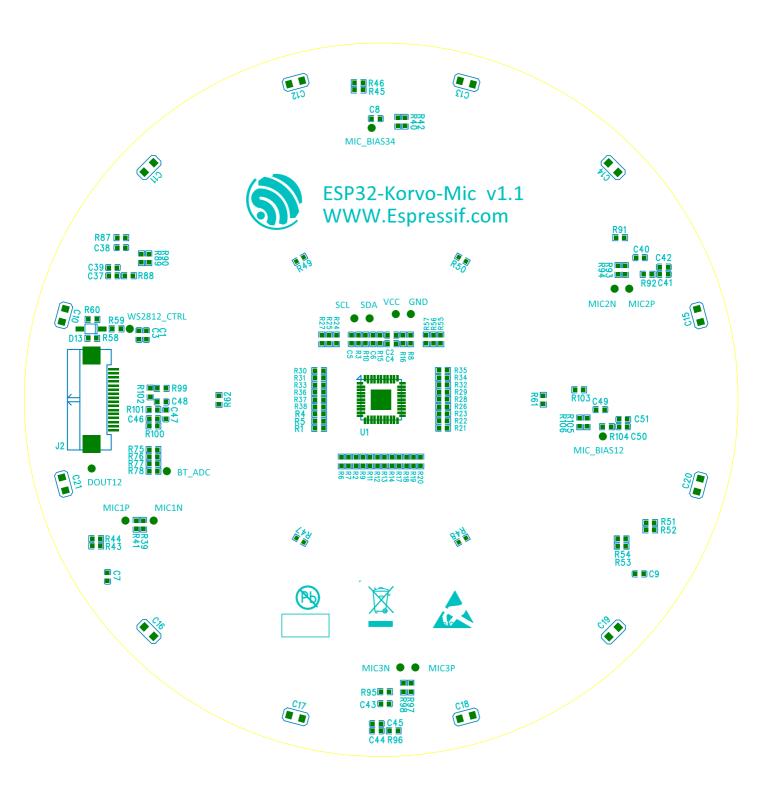
ESPF	RESSIF SYSTEM	
乐森信	(息科技(上海)股份有限公司	
Title	ESP32-Korvo-Mic	Rev L1
Task	#31025	
Date	2020.03.16 Mon.	

L1:TOP	展	材料 (FR4)	厚度(mil)
Prepreg	L1_TOP	10Z	1.4
L2:GND		PP(2116*2)	8.6
Core	L2_GND	10Z	1.4
L3:POWER		Core(可谓)	32
Prepreg	L3_POWER	10Z	1.4
L4:Bottom		PP(2116*2)	8.6
	L4_BOTTOM	10Z	1.4
	10 mount		



ESPE	RESSIF SYSTEM	
乐森性	(息科技(上海)股份有限公司	
Title	ESP32-Korvo-Mic	Rev 11
Task	#31025	
Date	2020.03.16 Mon.	

L1:TOP	86	HIII (FR4)	7F50mit
Proprieg	L1_TOP	102	1.4
L2:GND		PP(211612)	8.6
Core	L2_GND	10Z	1.4
LIFOWER		Core(可谓)	32
	L3_POWER	10Z	1.4
L4 Bottom		PP(211612)	8.6
	L4_BOTTOM	10Z	1.4



L1:T0P	88	材料 (FR4)	(lim)更限
Prepreg	L1_TOP	102	1.4
L2:GND		PP(2116*2)	8.6
Core	L2_GND	102	1.4
L3:POWER		Core(ii)(ii)	32
Prepreg	L3_POWER	102	1.4
L4:Bottom		PP(2116'2)	8.8
	L4_BOTTOM	102	1.4
	/0.063338		1000

ESPRI	ESSIF SYSTEM	
示直信	息科技(上海)股份有限公司	
Title	ESP32-Korvo-Mic	Rev
Task	W31025	
Date	2020.03.16 Mon.	